L Number	Hits	Search Text	DB	Time stamp
1	718899	die or chip$1	USPAT; US-PGPUB; JPO	2004/09/19 15:23
2	50864	wire near2 bond$3	USPAT; US-PGPUB; JPO	2004/09/19 15:23
3	1122235	semiconduct$3 or silicon	USPAT; US-PGPUB; JPO	2004/09/19 15:23
4	156850	encapsulat$3	USPAT; US-PGPUB; JPO	2004/09/19 15:24
5	899	(heat$3 or thermal$3) near2 slug	USPAT; US-PGPUB; JPO	2004/09/19 15:24
6	15764	solder$4 near2 ball$1	USPAT; US-PGPUB; JPO	2004/09/19 15:24
7	65582	(cavity or cavities or opening$1) same (pcb or board)	USPAT; US-PGPUB; JPO	2004/09/19 15:25
8	175509	(cavity or cavities or opening$1) same (pcb or board$1 or substrate$1)	USPAT; US-PGPUB; JPO	2004/09/19 15:26
9	157745	(die or chip$1) same (semiconduct$3 or silicon)	USPAT; US-PGPUB; JPO	2004/09/19 15:26
10	15437	encapsulat$3 same (die or chip$1)	USPAT; US-PGPUB; JPO	2004/09/19 15:26
11	95	((heat$3 or thermal$3) near2 slug) same ((cavity or cavities or opening$1) same (pcb or board$1 or substrate$1))	USPAT; US-PGPUB; JPO	2004/09/19 15:26
12	6028	((die or chip$1) same (semiconduct$3 or silicon)) and (encapsulat$3 same (die or chip$1)) and (wire near2 bond$3) and encapsulat$3	USPAT; US-PGPUB; JPO	2004/09/19 15:27
13	2193	(((die or chip$1) same (semiconduct$3 or silicon)) and (encapsulat$3 same (die or chip$1)) and (wire near2 bond$3) and encapsulat$3) and (solder$4 near2 ball$1)	USPAT; US-PGPUB; JPO	2004/09/19 15:27
14	56	((((die or chip$1) same (semiconduct$3 or silicon)) and (encapsulat$3 same (die or chip$1)) and (wire near2 bond$3) and encapsulat$3) and (solder$4 near2 ball$1)) and ((heat$3 or thermal$3) near2 slug)	USPAT; US-PGPUB; JPO	2004/09/19 15:27
15	22	(((heat$3 or thermal$3) near2 slug) same ((cavity or cavities or opening$1) same (pcb or board$1 or substrate$1))) and ((((die or chip$1) same (semiconduct$3 or silicon)) and (encapsulat$3 same (die or chip$1)) and (wire near2 bond$3) and encapsulat$3) and (solder$4 near2 ball$1))	USPAT; US-PGPUB; JPO	2004/09/19 15:27
16	56	(((((die or chip$1) same (semiconduct$3 or silicon)) and (encapsulat$3 same (die or chip$1)) and (wire near2 bond$3) and encapsulat$3) and (solder$4 near2 ball$1)) and ((heat$3 or thermal$3) near2 slug)) or ((((heat$3 or thermal$3) near2 slug) same ((cavity or cavities or opening$1) same (pcb or board$1 or substrate$1))) and ((((die or chip$1) same (semiconduct$3 or silicon)) and (encapsulat$3 same (die or chip$1)) and (wire near2 bond$3) and encapsulat$3) and (solder$4 near2 ball$1)))	USPAT; US-PGPUB; JPO	2004/09/19 15:27